UM1B-10~UM10B-10

Rev.D May.-2017

蓝箭电子
BLUE ROCKET ELECTRONICS
DATA SHEET

描述 / Descriptions

1.0A 表面贴装玻璃钝化整流桥，薄型 UMB 封装。
1.0A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

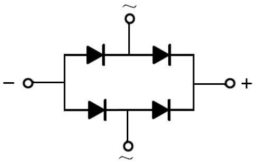
特征 / Features

玻璃钝化芯片，浪涌电流大，反向电压：100V~1000V，正向电流：1.0A，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V, Forward Current:1.0A, Designed for Surface Mount Application. HF product.

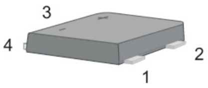
用途 / Applications

一般用途.
General purpose.

内部等效电路 / Equivalent Circuit

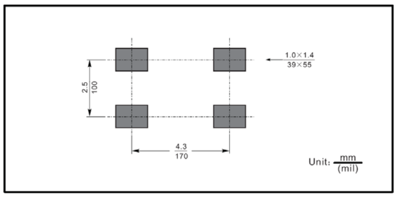


引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25℃)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		UM1B-10	UM2B-10	UM4B-10	UM6B-10	UM8B-10	UM10B-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 115℃	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance （Note1）	C_i	13						pF
Typical Thermal Resistance （Note2）	$R_{\theta JA}$ $R_{\theta JC}$	85 25						℃/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150						℃

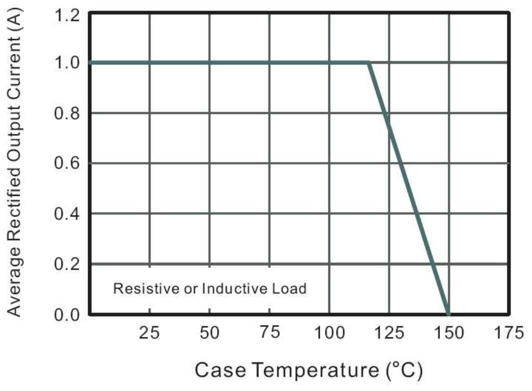
Note:

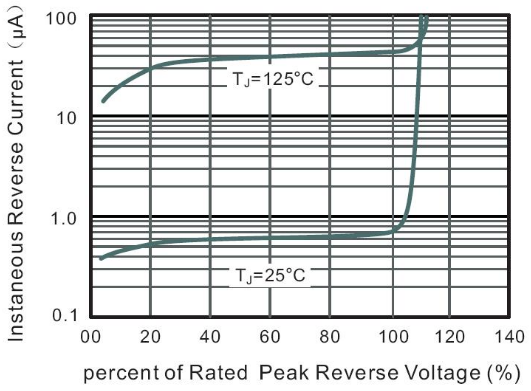
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5″ x1.5″ (3.81x3.81cm) copper pad areas.

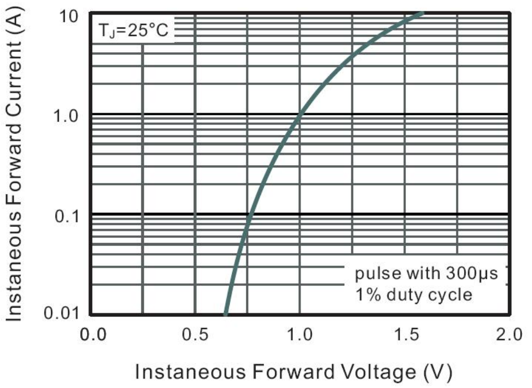
电性能参数 / Electrical Characteristics(Ta=25℃)

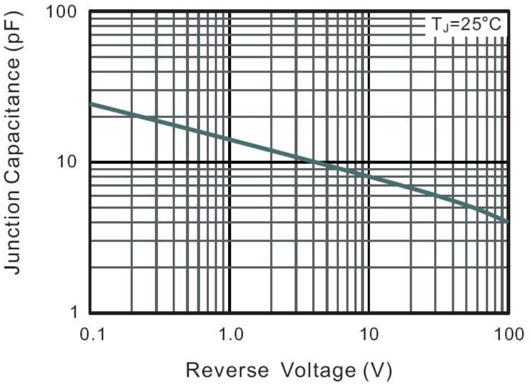
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	I_F=1.0A	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	5.0	μA
		T_a=125℃	40	

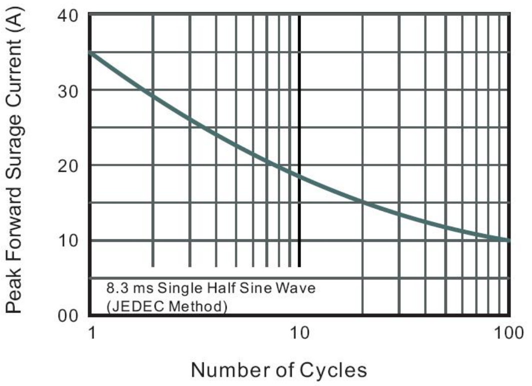
电参数曲线图 / Electrical Characteristic Curve





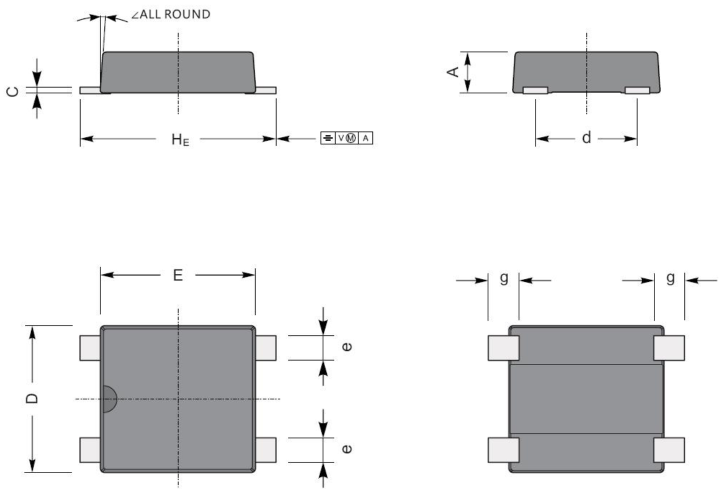






外形尺寸图 / Package Dimensions

UMB



UMB mechanical data

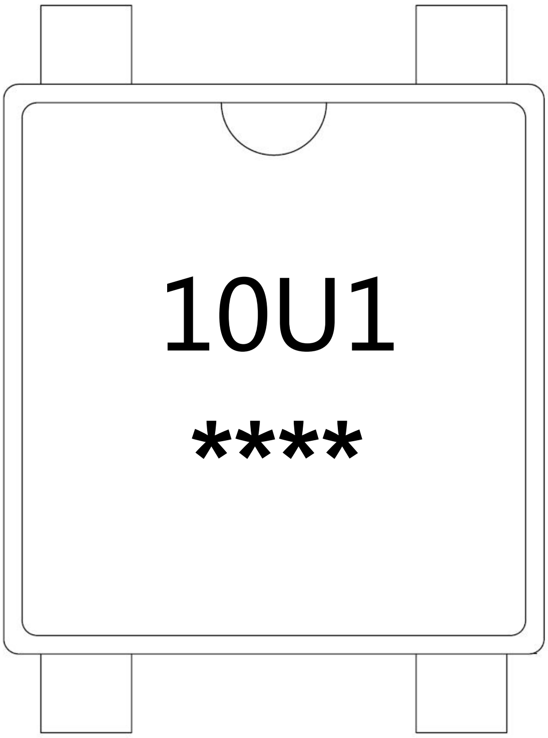
UNIT		A	C	D	E	H_E	g	d	e	∠
mm	max	1.2	0.20	3.8	4.0	5.1	0.82	2.7	0.70	7°
	min	1.0	0.12	3.4	3.6	4.6	0.51	2.3	0.51	
mil	max	47	7.9	150	157	201	32	106	28	
	min	39	4.7	134	142	181	20	91	20	

印章说明 / Marking Instructions

Marking

Type number	Marking code
UM1B-10	10U1
UM2B-10	10U2
UM4B-10	10U4
UM6B-10	10U6
UM8B-10	10U8
UM10B-10	10U10

印章说明 / Marking Instructions



说明：

10U1： 为型号代码

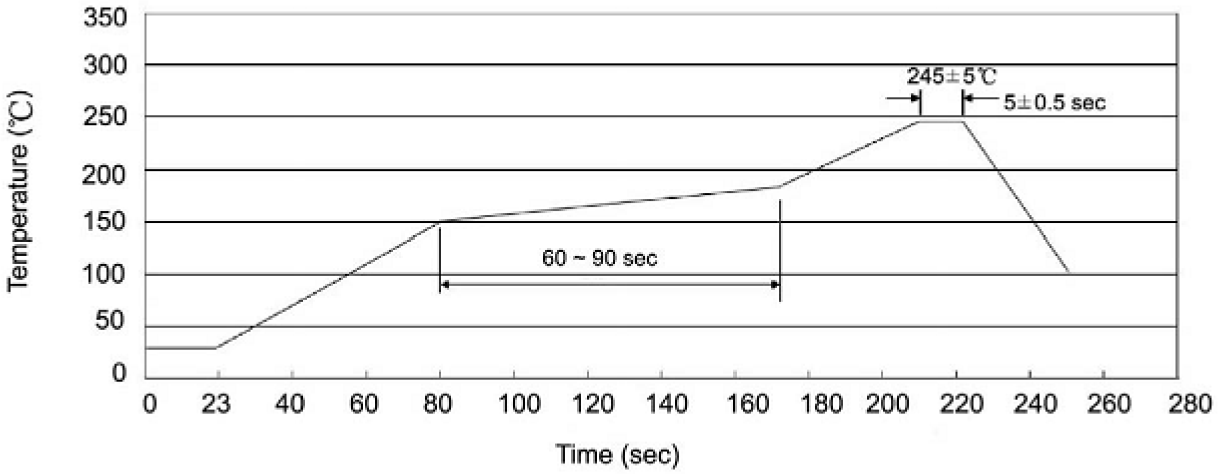
****： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

10U1： Product Type Code

****： Lot No. Code，The 1st * means:YM Code，The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：
1、预热温度 25～150℃，时间 60～90sec;
2、峰值温度 245±5℃，时间持续为 5±0.5sec;
3、焊接制程冷却速度为 2～10℃/sec.

Note:
1.Preheating:25~150℃, Time:60~90sec.
2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec.

Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
UMB	5000	2	10,000	5	50,000	13″ ×16	340 × 340 × 40	350 × 350 × 230

使用说明 / Notices